IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 10/550,829

Filing Date: Sept. 23, 2005

Applicant(s): Mahlkow et al.

For: Solution for Etching

Copper Surfaces and Method of Depositing Metal on Copper Surfaces

Examiner: Roberts P. Culbert

Art Unit: 1763

Attorney

Docket No.: 295-05

Confirm. No.: 1743

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action of June 6, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.

This submission is timely filed on or prior to September 6, 2007. No fees are believed to be required. In the event that an additional fee is required with respect to this communication, the Commissioner is hereby authorized to charge any additional fees, or credit any overpayment, to Paul & Paul Deposit Account No.16-0750.

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being transmitted to the U.S. Patent and Trademark Office via the EFS-Web electronic filing system of the U.S. Patent and Trademark Office

on September 6, 2007.

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Typed or printed name of person signing this

certificate: Antranig Baronian

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